An overview on solid-state-drives architectures and enterprise solutions

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What is a flash memory cell?

- Flash memory was invented by Dr. Fujio Masuoka in 1984
- The name "Flash" was adopted because the process of erasing the memory contents reminded him of the flash of a camera
- A Flash memory cell is a Floating Gate Metal-Oxide-Semiconductor Field-Effect Transistor (MOSFET)



What is a flash memory cell?

Anatomy

- The N+ region is a silicon lattice with phosphorus impurities, creating an **excess of electrons**
- The P- region is a silicon lattice with boron impurities, creating an **absence of electrons**
- The floating gate is surrounded by insulating layers



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- Applying a voltage between Control Gate (CG) and Body (P-well) creates a concentration of electrons between S and D
- If the voltage if high enough (V₁), it creates a channel between S and D which allows the current I_D to flow between them.



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 Applying an appropriate voltage (V_{PROGRAM}) to CG, the electrons will be trapped in FG



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Program operation

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- those electrons are kept in FG, although there is no tension on CG
- we call this state "0"
- In state 0, a voltage $V_0 > V_1$ is required in order to establish the N-channel



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- In state 0, electrons are stored in FG
- a voltage (*V_{ERASE}*) is required in order to remove them from FG
- at this point no charges are on FG
- we call this state "1"



How does a flash memory cell work? States of a Single-Level Cell

• The two states allows a cell to store a bit

STATE 1:

- No charges in FG
- required a $V_{CG} > V_1$ in order to set-up the N-Channel $\Rightarrow I_D > 0$

STATE 0:

- Charges are in FG
- required a $V_{CG} > V_0 > V_1$ in order to set-up the N-Channel $\Rightarrow I_D > 0$



Since the cell stores ONE bit, it is called Single-Level Cell (SLC)

How to write a cell?

• Erase the cell



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- If $I_D^* \neq 0$ the bit value is 1



Multi-Level Cell

- If we partially charge FG, we need a lower threshold voltage for creating a channel
- We store 2 bits by using 1 programmed state, 2 partially programmed states and 1 erased state
- A flash cell storing multiple bits is a Multi-Level Cell (MLC)
- A Triple-Level Cell (TLC) stores 3 bits



Why does a flash cell deteriorate in time?

- writing a flash cell involves an erase and a program
- \Rightarrow electrons move from/into FG

New Oxide

anode interface



cathode interface

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 - electrons collide with and damage the insulating layer creating traps
- \Rightarrow a Stress Induced Leakage Current (SILC) can flow through these traps



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- \Rightarrow a Stress Induced Leakage Current (SILC) can flow through these traps
 - a lot of traps can build a path from the body to FG
- \Rightarrow electrons can flow through that path $\Rightarrow impossibility$ to program
- \Rightarrow the flash cell is unusable



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Why does a flash cell deteriorate in time? PE-Cycles

 A flash cell can be programmed and erased a limited number of times before a breakdown ⇒ This number is called P/E-Cycles
Vendors design firmware capable of recompute the voltage

thresholds for read/write operations \Rightarrow enterprise-MLC (eMLC)



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$\mathsf{MLC} \mathsf{ vs} \mathsf{ SLC}$

SLC:

- lower density
- higher cost
- faster write
- faster read
- higher endurance

MLC:

- higher density
- lower cost
- erase time is similar to SLC
- the level of charges in FG has to be set carefully \Rightarrow slower program \Rightarrow slower write
- state is not $0/1 \Rightarrow$ slower read
- eMLC has 3x shorter endurance
- MLC has 10x shorter endurance
- TLC has 20x shorter endurance


1 bit















How are flash cells organized?

- Flash cells are connected forming an array called string
- According to the strategies used to connect multiple cells, we can distinguish at least two kind of configuration:

NOR

Flash cells are connected in parallel, resembling a NOR gate



NAND

Flash cells are connected in series, resembling a NAND gate



How are flash cells organized?

• Let F be the CG side length

NOR:

- occupies area 10F²
- read/write a single cell

NOR ARCHITECTURE



NAND:

- occupies area 4F²
- read/write a single page
- erase a single block

NAND ARCHITECTURE



NOR vs NAND

NOR:

- fast random-byte read
- slower page read
- slower write
- lower density
- \Rightarrow good for source code

NAND:

- no random-byte read
- slow partial page read when supported
- faster page read
- faster page write
- higher density
- \Rightarrow good for storage

We focus on NAND flash technology

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- \Rightarrow If we update the page 40 times per second (every 25ms), the block is completely broken in:

$$\circ SLC = \frac{PECycles}{UpdateRate} = \frac{10^5}{40ps} \approx 2500s \approx 40m$$

$$\circ MLC = \frac{10^4}{40ps} \approx 4m$$

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ALERT!

In our example the write rate is 80KBps

Write Amplification

- Write amplification occurs when 1 user page write leads to multiple flash writes
- Write amplification make flash blocks deteriorate faster
- Let F be the number of flash writes corresponding to U user writes
- \Rightarrow The write amplification A is:

$$A = \frac{F+U}{U} = 1 + \frac{F}{U} = 1 + A_f$$

where A_f is the write amplification factor

• Write-in-place is inadequate in terms of reliability and performance ($A_f \approx \#$ number of pages in a block)



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- The logical address of the update page is mapped to a different physical page
- Previous pages are invalidated
- \Rightarrow 1 user page write = 1 page read (obtain an empty page) + 2 page write (update data + invalidate page) \Rightarrow faster write



Flash Translation Layer

- Assign Logical Addresses to pages
- Store the association between physical and logical addresses in a Translation Mapping Table
- Store the number of erase operation performed on physical pages in a Erase Count Table
- Tables are:
 - maintained in SRAM (high efficient) at runtime
 - o stored on flash during shutdown to ensure durability
 - loaded at boot-up

Wear-Leveling

- Free pages for relocation can be retrieved from the whole SSD
- Wear-leveling guarantees that the number of PE-Cycles is uniformly distributed among all blocks
- $\Rightarrow\,$ Wear-leveling extends the time to live of each block and the whole SSD
 - Thanks to wear-leveling all blocks break at the same time



- In order to guarantee that enough free pages are available for write relocation, wear-leveling needs:
 - Over-provisioning keep free a percentage of raw capacity
 - Garbage collection keep invalid pages in the same block
 - **DRAM buffers** keep valid pages in a buffer in order to write full blocks and reduce fragmentation
- We can distinguish at least two kind of wear-leveling algorithms:
 - Dynamic wear-leveling
 - Static wear-leveling



- It is called dynamic, because it is executed every time the OS replace a block of data
- A small percentage (e.g. 2%) of raw capacity is reserved as free-block pool
- It chooses from the free pool the block with minimum erase count the buffer is flushed
- The replaced block is erased and added to the free pool
- \Rightarrow Only frequently-updated blocks are consumed



- Periodically scan the metadata of each block
- Individuate inactive data blocks with lower erase count than free blocks
- Copy their content into free-blocks and exchange them
- $\Rightarrow\,$ this guarantees that static blocks participate to wear leveling

At first approximation, wear-leveling eliminate write amplification generated by different sizes of erase and write units

 \Rightarrow The block time to fault is:

$$Block_{TTF} \approx rac{N_{die} \cdot N_{planes} \cdot N_{blocks} \cdot N \cdot PECycles}{PageWriteRate}$$

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$$\textit{Block_{TTF}} \approx \frac{\textit{Capacity}_{\textit{SSD}} \cdot \textit{PECycles}}{\textit{WriteRate}}$$

• Blocks deteriorate uniformly, thus:

$$Block_{TTF} \approx SSD_{TTF}$$

Wear-Leveling

Example

- Take a SSD with capacity C and a write rate W
- According to the flash cells used, we have different time to fault:

Wear-Leveling Example

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•
$$C = 4GB, W = 80KBps$$

• $SLC \Rightarrow SSD_{TTF} = \frac{C \cdot PECycles_{SLC}}{W} = \frac{4GB \cdot 10^5}{80KBps} \approx 158years$
• $MLC \Rightarrow SSD_{TTF} = \frac{C \cdot PECycles_{MLC}}{W} \approx 15.8years$
• $TLC \Rightarrow SSD_{TTF} = \frac{C \cdot PECycles_{TLC}}{W} \approx 7.9years$

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•
$$C = 128GB, W = 4MBps$$

• $SLC \Rightarrow SSD_{TTF} = \frac{C \cdot PECycles_{SLC}}{W} = \frac{128GB \cdot 10^5}{4MBps} \approx 101$ years
• $MLC \Rightarrow SSD_{TTF} = \frac{C \cdot PECycles_{MLC}}{W} \approx 10$ years
• $TLC \Rightarrow SSD_{TTF} = \frac{C \cdot PECycles_{TLC}}{W} \approx 5$ years

As said before wear leveling make flash blocks deteriorate uniformly. Anyhow

- Garbage collection increase the number of flash write
- Static Wear-leveling increases the number of flash write

 \Rightarrow re-introduce write amplification factor

$$SSD_{TTF} pprox rac{Capacity_{SSD} \cdot PECycles}{(1+A_f)WriteRate}$$

SSD Architecture



SSD Architecture




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- Reducing the amount of user data effectively stored in flash chips allows to reduce the write rate and increase the life of flash drives
- Data reduction techniques are:
 - Compression
 - Deduplication

- It consists in reducing the number of bits needed to store data.
- Lossless compression allows to restore data to its original state
- Lossy compression permanently eliminates bits of data that are redundant, unimportant or imperceptible
- CompressionRatio = <u>UncompressedSize</u> CompressedSize

$$\Rightarrow$$
 Data reduction is $DR_c = \frac{1}{CompressionRatio}$

$$SSD_{TTF} \approx rac{Capacity_{SSD} \cdot PECycles}{WriteRate \cdot (1 + A_f) \cdot DR_c}$$

Data Reduction Data Deduplication

- It looks for redundancy of sequences of bytes across very large comparison windows.
- Sequences of data are compared to the history of other such sequences.
- The first uniquely stored version of a sequence is referenced rather than stored again
- Let *DD* the average percentage of deduplicable data $SSD_{TTF} \approx \frac{Capacity_{SSD} \cdot PECycles}{WriteRate \cdot (1 + A_f) \cdot DR_c \cdot (1 - DD)}$

- RAID uses redundancy (e.g. a parity code) to increase reliability
- Any RAID solution increase the amount of data physically written on disks (RAID Overhead)
- ⇒ when adopting a RAID solution with flash technology we are reducing the lifetime of the whole storage system by a factor at most equal to the RAID overhead

- \bullet N flash disks of capacity C and cells supporting L P/E-cycles.
- Write load rate equal to W.

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Alert!

In order to increase reliability we half the time to live of flash cells

$SSD_{TTF} \approx rac{Capacity_{SSD} \cdot PECycles}{WriteRate \cdot (1 + A_f) \cdot DR_c \cdot (1 - DD) \cdot Overhead_{RAID}}$







Does it still make sense to use RAID?

- We have learned that any redundancy reduces the maximum time to live of all SSDs
- The answer is **YES**, but why?

Does it still make sense to use RAID?YES! Why?



Does it still make sense to use RAID?YES! Why?



EMC XtremIO

EMC²

- The system building block is called XBrick:
 - $\circ~$ 25 800GB eMLC SSDs
 - Two 1U Storage Controllers (redundant storage processors)
- The scale up is guaranteed by adding more XBricks (up to six in a rack) that will be connected through InfiniBand ports.
- The system performs inline data reduction by:
 - deduplication
 - compression





- The system checks for deduplicated data:
 - $1. \ \mbox{subdivide the write stream in 4KB blocks}$
 - 2. for each block in the stream
 - 2.1 compute a digest
 - $2.2\,$ check in a shared mapping table the presence of the block
 - 2.3 if present update a reference counter
 - 2.4 else use the digest to determine the location of the block and send the block to the respective controller node
- The addressing of blocks should uniformly distribute the data on all nodes

EMC XtremIO

XtremIO Data Protection

• The XtremIO system implements a proprietary data protection algorithm called XtremIO Data Protection (XDP)

EMC²

- Disks in a node are arranged in 23+2 columns
- 1 row parity and 1 diagonal party
- Each stripe is subdivided in 28 rows and 29 diagonals



EMC XtremIO XtremIO Data Protection

- In order to compute efficiently the diagonal parity and to spread writes on all disks, XDP waits to fill in memory the emptiest stripe
- When the stripe is full, commit it on disks
- The emptiest stripe selection implies that free space is linearly distributed on stripes
- XDP can:
 - o overcome 2 concurrent failures (2 parities)
 - $\circ~$ have a write overhead smaller than other RAID solutions

EMC XtremIO XtremIO Data Protection

EMC²

Suppose a system that is 80% full:

- The emptiest stripe is 40% full (due to the emptiest selection)
- A stripe can handle $28 \cdot 23 = 644$ writes
- The emptiest stripe can handle $644\cdot 40\%\approx 257$

$$\# parities = 28(rows) + 29(diagonal) = 57$$
$$RAIDoverhead = \frac{\# writes}{\# userwrites}$$
$$RAIDoverhead = \frac{257 + 57}{257} 1.22$$

IBM FlashDrive V840



- The system building block is made of:
 - $\circ~$ One Storage Enclosure of 12 4TB eMLC SSDs
 - Two Control Enclosures (redundant storage processors) with 8-core Intel Xeon and 32GB of RAM
- The system performs inline data reduction by:
 - $\circ\;$ compression with two dedicated hardware accelerators



IBM FlashDrive V840 2D RAID



- FlashDrive V840 offers two levels of RAID protection:
 - \circ RAID5 in configuration 10 +1 Parity +1 Spare among disks
 - $\circ~$ RAID5 in configuration 9+1 among chips in a disk
 - \circ RAID overhead = 4





- One storage enclosure equipped with:
 - $\circ~$ 2 controller nodes with 2 Intel eight-core processors and 32GB of RAM
 - 24 SSD drives
 - according to the type of flash cells, drives capacity is: 1920GB (MLC), 400GB (eMLC), 200GB (SLC);
- The system performs inline data reduction by:
 - deduplication which uses a hashing engine capability built into ASICs



Data Protection





Data Protection





Data Protection





Data Protection



More detailed info can be found in the main references:

- http://www.csee.umbc.edu/~squire/images/ssd1.pdf
- XtremIO, FlashDrive v840, HP 3PAR white papers

If you want to play, there is an interesting tool by Intel:

• http://estimator.intel.com/ssdendurance
Quick look to the (not-far) future



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